



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0307-02** DATE: 8/1/03
 Product Affected: IDT74FCT3244, IDT74FCT3245
 IDT74FCT244T, IDT74FCT245T
 Date Effective: October 31, 2003

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark
 Back Mark
 Date Code Prefix (Stepping) change. Please see attachment for details.
 Other

Contact: Bimla Paul
 Title: Quality Assurance Manager Attachment: Yes No
 Phone #: (408)-654-6419
 Fax #: (408)-492-8362 Samples: Available upon request.
 E-mail: bimla.paul@idt.com

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process Device stepping (revision) change from "PB" to "Z" on selected Logic products.
- Assembly Process There is no change in die technology.
- Equipment
- Material Please see attachment for the affected part numbers and qual data.
- Testing
- Manufacturing Site
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ***Approval for shipments prior to effective date.***
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: L0307-02

PCN Type: Die Revision Change

Data Sheet Change: None

Detail of Change: Device stepping (revision) change from "PB" to "Z" on selected Logic products. There is no change in die technology or fab location.

The following devices are affected by this change. All packages and speed grades are affected.

Part Number	Old Stepping	New Stepping
IDT74FCT3244	PB	Z
IDT74FCT3245	PB	Z
IDT74FCT244T	PB	Z
IDT74FCT245T	PB	Z

Conversion Schedule:

Die Revision

Z Stepping

Sample Availability:

August 15, 2003

Production Shipment:

October 31, 2003



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: L0307-02

Qualification Plans: Following reliability tests were performed on the process family. The qualification results are as follow:

Test Description	Test Method	Required Sample/ # Fails	Process Family Data	Z Stepping Data
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	Mil-Std 883 Method 1005	116/0	116/0	ECD Sept 15, 03
Bake & Ball Shear	EIA/JESD 22 B116	5/0	5/0	
Temp Cycle -65°C to +150°C, 500 Cyc	JESD 22 A104	45/0	45/0	
ESD Human Body Model	Mil-Std 883 Method 3015	3/0	3000V	ECD Sept 15, 03
ESD Charged Device Model	JEDEC 22-101	3/0	1000V	ECD Sept 15, 03
Latch up: (Tested to 1.5X Vcc)	EIA/JESD STD-78	10/0	10/0	ECD Sept 15, 03

ECD = Estimated Completion Date

Characterization Data:

Characterization data is available upon request.